

ADMETA 2014 AWARD NOTICE

8 Dec., 2014

The committee of Advanced Metallization Conference 2014 Asian Session has decided, following the evaluation process, give this year's awards to the following papers:

ADMETA AWARD

Authors: A. Isobayashi, M. Wada, B. Ito, T. Saito, D. Nishide, T. Ishikura, M. Katagiri, Y. Yamazaki, T. Matsumoto, M. Kitamura, M. Watanabe, N. Sakuma, A. Kajita and T. Sakai (Low-power Electronics Association & Project)

Paper Title: CNT Via Integration with Highly Dense and Selective CNT Growth

Paper Number: 4-5

TECHINCAL ACHIEVEMENT AWARD

Authors: Osamu Nakatsuka, Yunsheng Deng, Mitsuo Sakashita, and Shigeaki Zaima (Nagoya University)

Paper Title: Formation of Epitaxial NiGe Layer on Ge(001) Substrate and Influence of Interface Structure on Schottky Barrier Height

Paper Number: 3-4

Authors: Hyun-Jung Lee¹, Seung-Joon Lee¹, Seungmin Yeo¹, Yujin-Jang¹, Taehoon Cheon^{1,2}, Tae Eun Hong³ and Soo-Hyun Kim¹ (¹Yeungnam University, ²Deagu Gyeonbuk Institute of Science & Technology, ³Korea Basic Science Institute)

Paper Title: Atomic layer deposited Ru-Mn alloy film as a Cu direct plateable diffusion barrier

Paper Number: 5-4

POSTER AWARD

Authors: Eiichi Kondoh, Yukihiro Tamegai, Mitsuhiro Watanabe and Lianhua Jin (University of Yamanashi)

Paper Title: Selective Cu fill into nanopores using supercritical carbon dioxide

Paper Number: P-2

An award ceremony will be held at the next ADMETA in 2015.